

MAINTENANCE MANUAL LOGIC BOARD

TMX-8415, TMX-8615 & TMX-8630

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DESCRIPTION

The logic board for the TMX-84 and TMX-86 series trunked mobile radios controls the operation of the radio. The logic board provides all of the necessary analog/digital processing, tones, codes and control functions. The logic circuitry controls channel acquisition, RF frequency selection, tone/code generation and detection, and operator interface functions. Interface functions include control panel displays and switch panel, audible alert tones, and test handset and programming functions.

The logic board contains the micro-processor, digital signal processor, external memory EPROM for the microprocessor, the programmable personality EEPROM, and two octal latches for the I/O microcomputer interface.

The logic board is mounted in the top section of the chassis above the transmitter/receiver/synthesizer (TRS) board. All power and control function interconnections are provided by cables CA11, CA12 and CA13.

Simplified diagrams and pin-out information on the Integrated Circuits are contained in the Service Sheet listed in the Table of Contents.

CIRCUIT ANALYSIS

The logic board contains the digital processing and initializing circuitry for the trunked mobile radio.

Digital processing circuitry consists of microprocessor A1, octal latches A2 and A11, EPROM A3, EEPROM 4, digital processor A5 and CODEC A6.

A3 is an 8K x 8 bit EPROM. It is used by the microcomputer to control all radio and system functions. Crystal Y1 and inverter A14 provide the time base to sequence the microcomputer through its internal software program, allowing it to execute the program stored in the program memory.

EEPROM A4 contains all data unique to the radio and is referred to as the Personality PROM. Information stored in the Personality PROM includes all area and group information (including RF channels and signalling tones) as well as all radio options (e.g. carrier control timer, hookswitch options, alert tone control, etc.)

A5 is a digital signal processor used to generate and detect signalling tones, provide filtering and control the exchange of serial data to and from CODEC A6. The digital processor utilizes 8 parallel data lines to interface with the microcomputer.

A simplified diagram of the digital processing circuitry is shown in Figure 1.

Power for the logic board is provided by a continuous 13.8 volts (A+), a switched 13.8 volts (SW A+), and a regulated +5 volts (Vcc) from the TRS board. A regulated +5 volts DC and -5 volts DC is derived from the switched A+.

OCTAL LATCHES A2 & A11

Octal latches A2 and A11 are used to exchange data passing between microprocessor A1, and the memory and control circuits respectively.



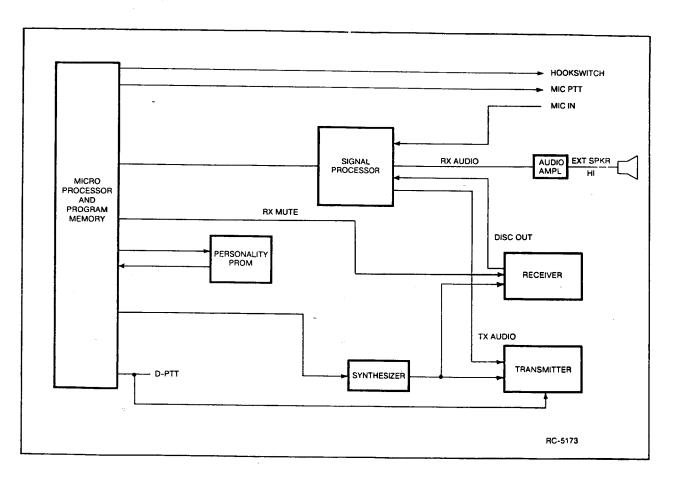


Figure 1 - Simplified Digital Processing Diagram

Octal latch A11 provides the interface between the microprocessor and the control panel switches. A11 is connected so that the latch function is disabled (the "G" input A11-11 connected to 5 volts) and the octal latch operates as a buffer for the microprocessor output.

Octal latch A2 has the "G" input connected to the ALE (address latch enable) output of the microprocessor to provide a latched address interface between the EPROM, and personality EEPROM.

RESET/MEMORY BACKUP

The microprocessor reset and memory backup circuit consists of 5-volt regulator A16, zener diode CR2, switching transistors Q1 and Q2, and pass transistor Q3.

Microprocessor A1 is reset by switched A+ (13.6 volts) on/off and programmer reset. The microprocessor resets when +5 volts is applied to RST input A1-9 from regulator A16 through pass transistor Q3.

In a power-down state (A+ SW off), zener diode does not conduct, keeping Q1 turned off. When Q1 is off Q2 conducts, turning on Q3. Turning on Q3 applies +5 volts from the collector of Q3 to reset pin 9 of U1. The 5-volt supply provides the memory backup for microprocessor A1, and keeps A1 in the reset state.

When the radio is turned on (A+ SW on), zener diode CR2 conducts, turning on Q1. Turning on Q1 turns Q2 and Q3 off. The +5 volts to A1-9 decays to about 0 volts as determined by the time constant of C3 and R6. When the voltage at A1-9 drops to approximately 0 volts, the microprocessor starts executing its program memory approximately 12 milliseconds after Q1 turns on and Q2 and Q3 turn off.

MICROPROCESSOR A1

Microprocessor Al directly interfaces with and controls the operation of all the digital processing circuitry. It also interfaces with the radio and control panel display functions through octal latch All and external buffer stages.

The microprocessor controls the operation of the radio by performing the following major functions:

- System Timing
- Frequency Selection
- Mode Selection
- Group Selection
- Transmit/Receive Control
- Test Handset Control and Display
- Audio Routing and Mute Control
- Maintenance Functions

Microprocessor A1 is sequenced through its program by an internal oscillator whose frequency is set by crystal Y1. The oscillator frequency is 8.192 MHz.

The microprocessor accesses its program memory from EPROM A3. Reading of the stored program at A3 occurs when the PSEN line of A1 is low. The upper eight address lines of A1 (A8-A15) are stationary during this access time. The lower eight address lines of A1 (ADO-AD7) are captured by octal latch A2 and held stationary. ALE (A1-30) is used to latch the lower eight address lines. The output of A3 is then read into the data bus (ADO-AD7) of A1.

The microprocessor interfaces with the microphone through MIC PTT and LOGIC HKSW. It also interfaces with the TQ2310 programmer through HKSW, MIC PTT, SER DAT and SP RESET on P1, and with the digital signal processor A5, and Personality EEPROM A4.

The microprocessor control signals include the following:

EA (Enable) - When low allows microcomputer to retrieve all instructions from external memory.

RST (Reset) - Resets microcomputer to beginning of software program when switched A+ is turned off, immediately following power interruptions or with low battery voltage. Also resets when a RST signal from the programmer is received.

SYN DATA - Data transferred to synthe sizer representing RF frequencies.

SYN CLOCK - Timing output to synthesizer.

SYN LOCK - A status input signal from the synthesizer to indicate frequency lock status of VCO.

RX MUTE (Receiver Mute) - Turns receiver audio off while operating in the trunked

mode during channel acquisition (idle and wait mode) and when transmitting.

D-PTT (Delayed PTT) - Energizes the antenna relay, and turns off the receiver front end and 1st RF amplifier. D PTT also switches the bilateral audio gates on the logic board in the transmit and receive mode.

MIC PTT - The microprocessor monitors the status of the switched PTT lead from the microphone. It also receives clock data on this line while the radio is being programmed.

RD, WR (Read, Write) - Allows the microprocessor to read/write data to/from EEPROM A4 and read/write from/to digital processor A5.

PSEN (Program Send Enable) - Allows the processor to read instructions from program memory A3.

ALE (Address Latch Enable) - Allows microcomputer to hold the eight least significant lines (ADO-AD7) stable by using octal latch A2. This is necessary when reading from program memory A3 or reading/writing from/to EEPROM A4.

A8-A15 (Address Lines) - Eight most significant address line. These are used to address and access the program memory, digital processor, and the EEPROM.

DIGITAL PROCESSOR A5

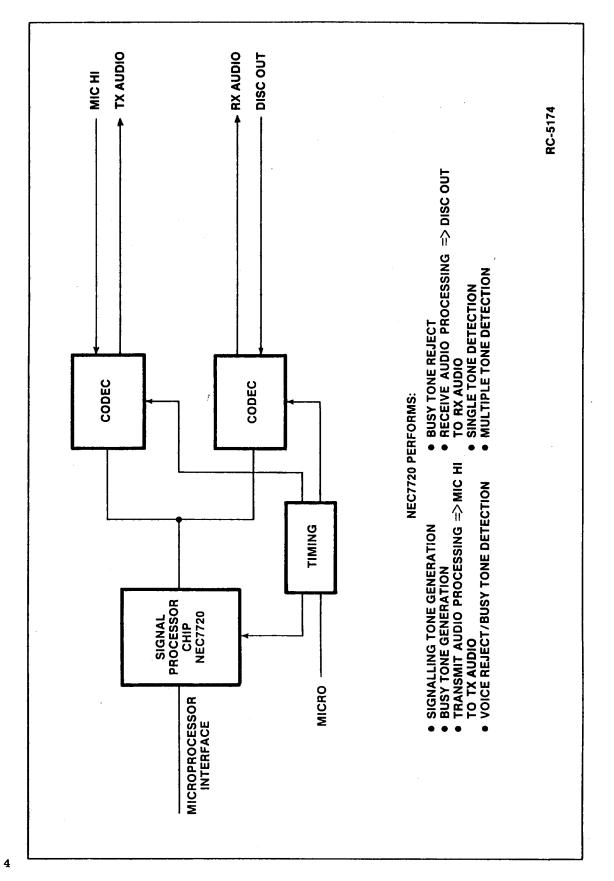
Digital processor A5 is a programmasked IC that operates under the control of microprocessor A1, and performs all processing on the digitized audio serial data stream from the CODEC, A6. The following functions are performed by the digital processor.

- Busy Tone Notching
- Signaling Tone Detection
- Busy Tone Detection
- Alert Tone Generation
- Receive Audio Processing
- Transmit Audio Processing

Transmit Audio Pre-emphasis

- Transmit Audio Limiter
- Busy Tone Injection
- Tone Generation

The digitized CODEC output is applied to A5-21 (Signal Input), and the processed output is applied to the CODEC on A5-22 (Signal Out). A simplified diagram of the digital processor is shown in Figure 2.



gure 2 - Simplified Digital Processor Diagra

CODEC A6

CODEC A6 provides the analog-to-digital and digital-to-analog conversions.

The following major functions are provided:

- Bandpass filtering of the analog signals prior to encoding and after decoding
- Encoding and decoding of voice and call progress information
- Encoding and decoding of the signalling and supervision information

Refer to Service Sheet for a Block Diagram of the CODEC A6.

The CODEC can be powered up by pulsing FSx and/or FSr while a TTL high voltage is applied to PDN, provided that all clocks and supplies are connected. The CODEC has internal resets on power up (or when Vbb or Vcc are re-applied) in order to ensure validity of the digital outputs and thereby maintain integrity of the PCM highway.

On the transmit channel, digital outputs Dx and TSx are held in a high impedance state for approximately four frames (500 us) after power up or application of Vbb or Vcc After this delay, Dx and TSx will be functional and will occur in the proper timeslot. The analog circuits on the transmit side require approximately 60 milliseconds to reach their equilibrium value due to the autozero circuit settling time.

To enhance system reliability $\overline{TS}x$ and Dx will be placed in a high impedance state approximately 30 us after an interruption of CLK.

Power Down and Standby Modes

To minimize power consumption, two power down modes are provided in which most functions are disabled. Only the power down, clock, and frame sync buffers, which are required to power up the device, are enabled in these modes. As shown in Table 1, the digital outputs on the appropriate channels are placed in a high impedance state until the device returns to the active mode.

The Power Down mode utilizes an external control signal to the \overline{PDN} pin. In this mode, power consumption is reduced to an average of 5 mW. The device is active when the signal is high and inactive when it is low. In the absence of any signal, the \overline{PDN} pin floats

to TTL high allowing the device to remain active continuously.

The Standby mode leaves the user an option of powering either channel lown separately or powering the entire device down by selectively removing FSx and/or FSr. With both channels in the standby state, power consumption is reduced to an average of 12 mW. If transmit only operation is desired, FSx should be applied to the device while FSr is held low. Similarly, if receive only operation is desired, FSr should be applied while FSx is held low.

Fixed Data Rate Mode

Fixed data rate timing is selected by connecting DCLKr to Vbb it employs master clock CLK, frame synchronization clocks FSx and FSr, and output $\overline{\text{TS}}$ x.

CLK serves as the master clock to operate the codec and filter sections and as the bit clock to clock the data in and out from the PCM highway. FSx and FSr are 8 kHz inputs which set the sampling frequency. TSx is a timeslot strobe/buffer enable output which gates the PCM word onto the PCM highway when an external buffer is used to drive the

Data is transmitted on the highway at Dx on the first eight positive transitions of CLK following the rising edge of FSx. Similarly, on the receive side, data is received on the first eight falling edges of CLK. The frequency of CLK must be 2.048 MHz. No other frequency of operation is allowed in the fixed data rate mode.

Variable Data Rate Mode

Variable data rate timing is selected by connecting DCLKr to the bit clock for the receive PCM highway rather than to Vbb. It employs master clock CLK, bit clocks DCLKr and DCLKx, and frame synchronization clocks FSr and FSx.

Variable data rate timing allows for a flexible data frequency. It provides the ability to vary the frequency of the bit clocks, from 64 kHz to 2.048 MHz. The master clock is still restricted to 2.048 MHz.

In this mode, DCLKr and DCLKx become the data clocks for the receive and transmit PCM highways. While FSx is high, PCM data from Dx is transmitted onto the highway on the next eight consecutive positive transitions of DCLKx. Similarly, while FSr is high, each PCM bit from the highway is received by Dr on the next eight consecutive negative transitions of DCLKr.

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CIRCUIT ANALYSIS

TABLE 1 - Power-Down Methods

Device Status	Power-Down Method	Typical Power Consumption	Digital Output Status
Power Down Mode	PDN = TTL low	5 mW	TSx and Dx are placed in a high impedance state within 10 us.
Standby Mode	FSx and FSr are are TTL low	12 mW	TSx and Dx are placed in a high impedance state within 300 milliseconds.
Only transmit is on standby	FSx is TTL low	70 mW	TSx and Dx are placed in a high impedance state within 300 milliseconds.
Only receive is on standby	FSr is TTL low	110 mW	

On the transmit side, the PCM word will be repeated in all remaining timeslots in the 125 us frame as long as DCLKx is pulsed and FSx is held high. This feature allows the PCM word to be transmitted to the PCM highway more than once per frame, if desired, and is only available in the variable data rate mode.

Precision Voltage Reference

No external components are required with the CODEC to provide the voltage reference function. Voltage references are generated on-chip and are calibrated during the manufacturing process. The technique uses a difference in sub-surface charge density between two suitably implanted MOS devices to derive a temperature and bias stable reference voltage. These references determine the gain and dynamic range characteristics of the device.

Separate references are supplied to the transmit and receive sections and each is trimmed independently during the manufacturing process. The reference value is then further trimmed in the gain setting op-amps to a final precision value.

TRANSMIT OPERATION

Transmit Filter

The input section provides gain adjustment in the passband by means of an on-chip operational amplifier. This operational amplifier has a common mode range of ±2.17 volts, a maximum DC offset of 25 mV, a minimum open loop voltage gain of 5000, and a unity gain bandwidth of typically 1 MHz. Gain of up to 20 dB

can be set without degrading the performance of the filter. The load impedance to ground (GRDA) at the amplifier output (GSx) must be greater than 10 kilohms in parallel with less than 50 pF. The input signal on lead VFxI- can be either AC or DC coupled.

A low pass anti-aliasing section is included on-chip. This section typically provides 35 dB attenuation at the sampling frequency. No external components are required to provide the necessary anti-aliasing function for the switched capacitor section of the transmit filter.

The passband section provides flatness and stopband attenuation.

A high pass section configuration was chosen to reject low frequency noise from 50 and 60 Hz power lines, 17 Hz European electric railroads, ringing frequencies and their harmonics, and other low frequency noise. Even though there is high rejection at these frequencies, the sharpness of the band edge gives low attenuation at 200 Hz. This feature allows the use of low-cost transformer hybrids without external components.

Encoding

The encoder internally samples the output of the transmit filter and holds each sample on an internal sample and hold capacitor. The encoder then performs an analog to digital conversion on a switched capacitor array. Digital data representing the sample is transmitted on the first eight data clock bits of the next frame.

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CIRCUIT ANALYSIS

LBI-31558

An on-chip autozero circuit corrects for DC-offset on the input signal to the encoder. This autozero circuit uses the sign bit averaging technique; the sign bit from the encoder output is long term averaged and subtracted from the input to the encoder. In this way, all DC offset is removed from the encoder input waveform.

RECEIVE OPERATION

Decoding

The PCM word at the Dr lead is serially fetched on the first eight data clock bits of the frame. A D/A conversion is performed on the digital word and the corresponding analog sample is held on an internal sample and hold capacitor. This sample is then transferred to the receive filter.

Receive Filter

The receive filter provides passband flatness and stopband rejection.

Receive Output Power Amplifiers

A balanced output amplifier is provided in order to allow maximum flexibility in output configuration. Either of the two outputs can be used single ended (referenced to GRDA) to drive single ended loads. Alternatively, the differential output will drive a bridged load directly. The output state is capable of driving loads as low as 300 ohms single ended or 600 ohms differentially.

The receiver output (DISC OUT) and microphone output (MIC IN) are applied to A6-14 and A6-15. After processing, the DISC OUT and MIC IN signals are applied to the TRS board as RX AUDIO and TX AUDIO. DR and DX are the data receive and data transmit lines from the digital processor.

The CODEC also receives outputs from counter, A7. The inputs include the transmit synchronization clock (FSx) receiver synchronization clock (FSr), transmit and receive data clocks (DCLKx and DCLKr), and master clock (CLK).

COUNTER A7

Counter A7 is a 12-stage, binary counter that provides the time base for CODEC A6 and digital processor A5. The counter receives the master clock input from the microprocessor oscillator Y1.

In addition to the clock outputs to CODEC A6 and the digital processor, the counter also applies a 32 kHz output to timer A21 to provide the analog -5 volts (-5 AV) for the CODEC.

+5 VOLT (AV) REGULATOR

Two 5-volt regulators are used to supply power to CODEC A6. Switched A+ is applied directly to the +5 AV (analog voltage) regulator A17 which in turn supplies the CODEC. The negative 5 Volts is generated by a power supply consisting of timer A21, rectifier CR3, and -5 VDC regulator A18. A 32 kHz signal from high speed counter A7 is applied to rectifiers CR3. The rectified negative voltage is applied to -5 volt regulator A18 which then supplies a regulated -5 AV to CODEC A6. The ±5-volt supply is also applied to the tri-stage bilateral gate A19.

EEPROM "WRITE" CONTROL

The EEPROM "WRITE" (WR) control consists of Q10 and Q11. When address bit A10 from the microprocessor is high, Q10 turns on and Q11 turns off. This applies +5 volts to the WR input which disables the "WRITE" function. When address bit A10 goes low, Q10 turns off and Q11 turns on. This applies a low to the WR input, enabling the WRITE function (if CS is low) which allows data to be written to the EEPROM. To WRITE to the memory, the WRITE input must be low, and the OE input must be high. In the RD mode, write is high OE is low, and CS is low.

The WR function can also be enabled by a low from programmer TQ2310 via SP store.

AUDIO SWITCH A19

Transmit and receiver audio signals at J3 are routed to and from the CODEC through a three-stage bilateral switch (A19). The switch stages are controlled by the D-PTT of the microprocessor. In the transmit mode, the MIC IN is processed and applied to buffer A20. The buffer output is coupled through MODULATION ADJUST R52 and applied to the VCO mod input on the TRS board.

In the receive mode (D-PTT low), DISC OUT from the receiver is processed and applied directly to the receiver audio amplifier at RX AUDIO.

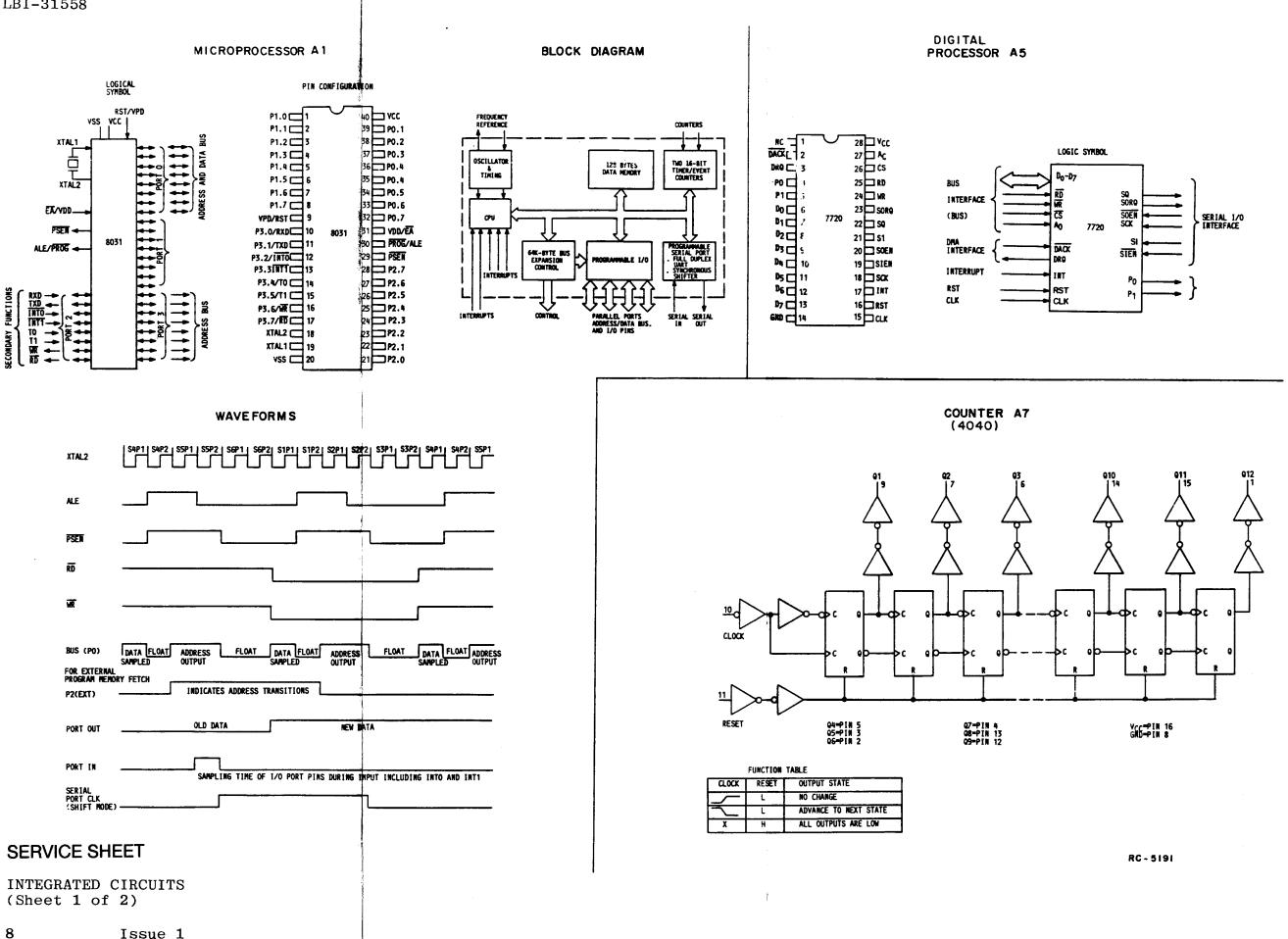
The switch is supplied by the ± 5 AV regulators.

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WORLD HEADQUARTERS • LYNCHBURG, VIRGINIA 24502 U.S.A.

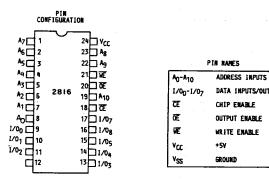


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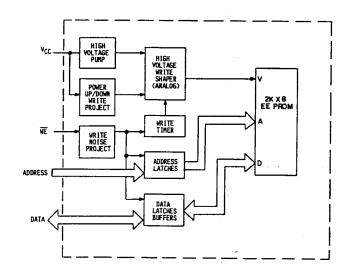
Issue 1



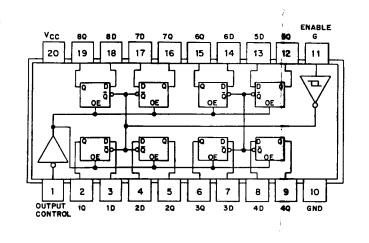
EE PROM A4



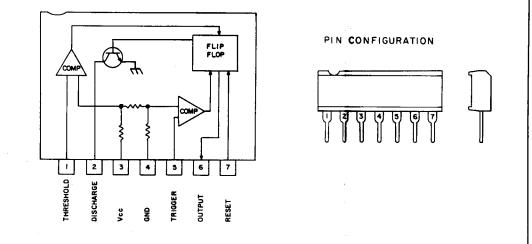
FUNCTIONAL DIAGRAM



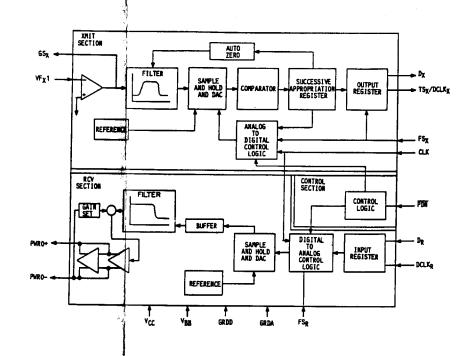


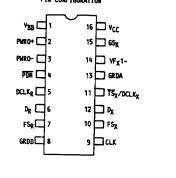


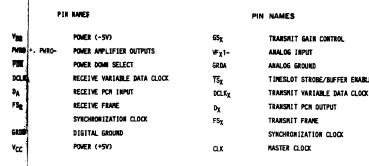
TIMER A21



CODEC A6







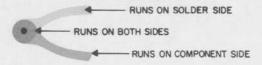
RC-5192A

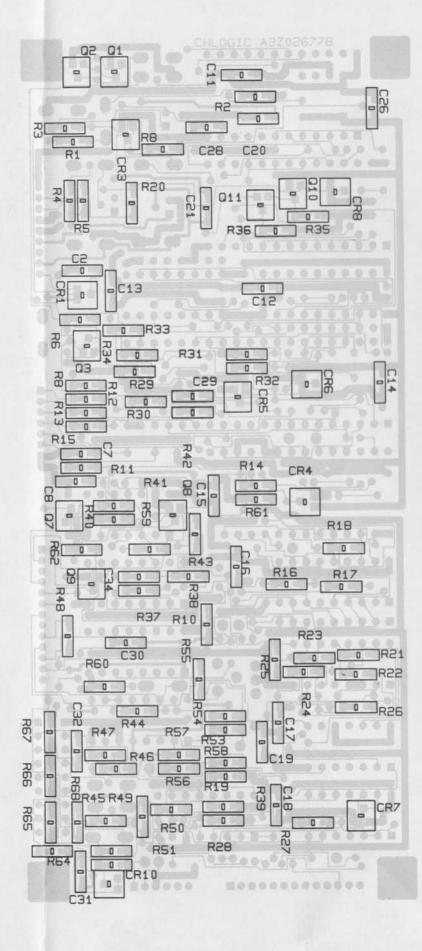
SERVICE SHEET

INTEGRATED CIRCUITS (Sheet 2 of 2)

Issue 2





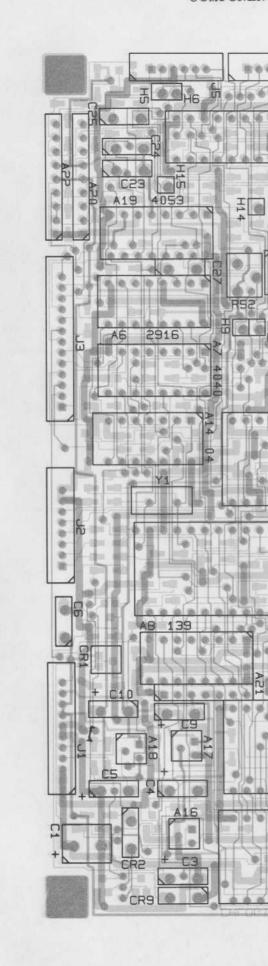


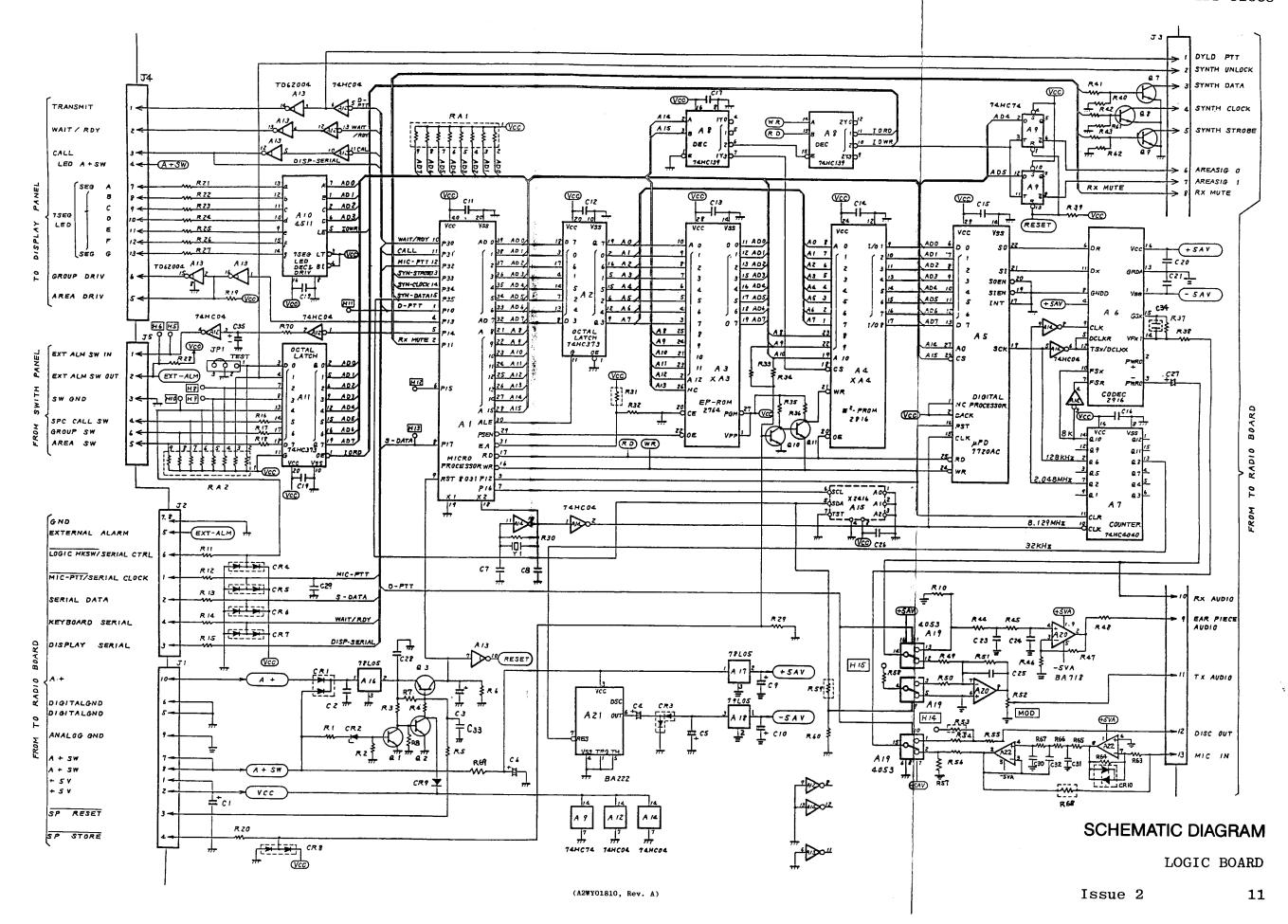
OUTLINE DIAGRAM

LOGIC BOARD

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Issue 2





PARTS LIST

LOGIC BOARD A4WE03583 ISSUE 2

A1	SYMBOL	PART NO.	DESCRIPTION
### REC/2AD005179 Micro Processor P8031AH. KEC/2ABD018102 TC74HC373p			INTEGRATED CIRCUITS
A3	A 1	KEC/2ADA005179	Micro Processor P8031AH.
A4 KEC/2AAR019021 CODEC A7 KEC/2AAR019021 CODEC A7 KEC/2AAR018021 TC74HC4040P A8 KEC/2AAR018018052 TC74HC74P A10 KEC/2ABD018052 TC74HC74P A11 KEC/2ABD018102 TC74HC373P A12 KEC/2AAR021014 TD82004P A13 KEC/2AAR021014 TD82004P A14 KEC/2AAR049181 TC74HC04P A15 KEC/2AAR049181 TC74HC04P A16 KEC/2AAR049181 TC74HC04P A17 KEC/2AAR049181 TC74HC04P A18 KEC/2AAR049181 TC74HC04P A19 KEC/2AAR0049179 TC74HC373P A19 KEC/2AAR039012 TC4053BP A20 KEC/2AAR039012 BA718 A21 KEC/2AAR039012 BA718 A21 KEC/2AAR039012 BA718 A22 KEC/2ACX005391 Ceramic chip, 0.01 uF. C6 KEC/2CCX005205 Fixed, tantalum 204M3502-105MB ±20%. C7 KEC/2CCX005391 Ceramic chip CH 10P ±0.5 pF, 50V. C8 KEC/2CAK005391 Ceramic chip CH 10P ±0.5 pF, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C9 KEC/2CCX005391 Ceramic chip, 0.01 uF 10%, 50V. C11 KEC/2CAK005391 Ceramic chip, 0.01 uF ±5%, 50V. C22 KEC/2CCX00391 Ceramic chip, 0.01 uF ±5%, 50V. C23 KEC/2CCX00391 Ceramic chip, 0.01 uF ±0%, 50V. C7 KEC/2CAK005391 Ceramic chip, 0.01 uF ±0%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.01 uF ±5%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.01 uF ±5%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.01 uF ±5%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.00 pF mH ±5%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.00 pF mH ±5%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.00 pF mH ±5%, 50V. C8 KEC/2CAK005391 Ceramic chip, 0.00 pF mH ±5%, 50V. C8 KEC/2CAK005392 Ceramic chip, 0.00 pF mH ±5%, 50V. C8 KEC/2CAK005393 Ceramic chip, 0.00 pF mH ±5%, 50V. C8 KEC/2CAK005393 Ceramic chip, 0.00 pF mH ±5%, 50V. C8 KEC/2CAK005393 Ceramic chip, 0.00 pF mH ±5%, 50V. C8 KEC/2CAK005393 Ceramic chip, 47 pF RH ±5%, 50V. C8 KEC/2CAK005393 Ceramic chip, 47 pF RH ±5%, 50V.	A2	j	
### ##################################	A 3	KEC/2ACA033108	EP-ROM M5L2764K
A6 KEC/2AB0018012 CODEC A7 KEC/2AB018012 TC74RC4040P A8 KEC/2AB018052 TC74RC74P A10 KEC/2AB018052 TC74RC74P A11 KEC/2AB018102 TC74RC74P A12 KEC/2AB018109 TC74RC04P A13 KEC/2AB018169 TC74RC04P A14 KEC/2AB018169 TC74RC04P A15 KEC/2AB0018169 TC74RC04P A16 KEC/2AAB049179 VTG-REG AN78L05 A17 KEC/2AAB049179 TC74RC04P A18 KEC/2AAB049179 TC74RC04P A19 KEC/2AAB049179 TC74RC04P A10 KEC/2AB0037012 TC40S3BP A21 KEC/2AAB039015 BA222 KEC/2AB039015 BA222 KEC/2CE0050391 CFixed, elect A1 KMA10VB100M. C2 KEC/2CAE005391 CFixed, tantalum 204M3502-105MB ±20%. C6 KEC/2CAE005391 CFixed, tantalum 204M3502-106M ±20%. C8 KEC/2CE001012 CFixed, tantalum 204M3502-106M ±20%. C9 KEC/2CAE005391 CFixed, tantalum 204M3502-106M ±20%. C11 KEC/2CAE005391 CFixed, tantalum 204M3502-106M ±20%. C8 KEC/2CAE005391 CFixed, tantalum 204M3502-106M ±20%. C11 KEC/2CAE005391 Fixed, tantalum 204M3502-106M ±20%. C11 KEC/2CAE005391 Fixed, film, ECQ-VIHI04J29 0.1 up ±5%, 50V. C23 KEC/2CAE005391 Fixed, film, ECQ-VIHI04J29 0.1 up ±5%, 50V. C24 KEC/2CCE003041 Fixed, film, ECQ-VIHI04J29 0.1 up ±5%, 50V. C28 KEC/2CAE005391 CFramic chip, 0.01 up ±10%, 50V. C29 KEC/2CAE005391 CFixed, film, ECQ-VIHI04J29 0.1 up ±5%, 50V. C28 KEC/2CAE005391 Fixed, film, ECQ-VIHI04J29 0.1 up ±5%, 50V. C28 KEC/2CAE005391 CFramic chip, 0.01 up ±10%, 50V. C28 KEC/2CAE005391 CFramic chip, 0.01 up ±5%, 50V. C28 KEC/2CAE005391 CFramic chip, 0.01 up ±5%, 50V. C29 KEC/2CAE005391 CFramic chip, 0.01 up ±5%, 50V. C28 KEC/2CAE005391 CFramic chip, 0.01 up ±5%, 50V. C29 KEC/2CAE005391 CFramic chip, 0.01 up ±5%, 50V. C28 KEC/2CAE005391 CFramic chip, 0.01 up ±5%, 50V. C29 KEC/2CAE005391 CFramic chip, 0.00 pp ±5%, 50V. C28 KEC/2CAE005391 CFramic chip, 0.00 pp ±5%, 50V. C29 KEC/2CAE005391 CFramic chip, 0.00 pp ±5%, 50V. C29 KEC/2CAE005391 CFramic chip, 0.00 pp ±5%, 50V. C29 KEC/2CAE005391 CFramic chip, 0.00 pp ±10%, 50V. C29 KEC/2CAE005391 CFramic chip, 0.00 pp ±10%, 50V. C29 KEC/2CAE005393 CFramic chip, 47 pp RH ±5%, 50V. C29 KEC/2CAE005330 CFramic chip, 47 pp RH ±5%, 50V.	A4	KEC/2ACA040087	EE PROM
A7	A 5		upD7720D-1 26
### REC/2ABD018078 #### REC/2ABD018052 ####################################	A6	KEC/2AAH019021	CODEC
REC/2ABD018052 TC74RC74P	A7	KEC/2ABD018512	TC74HC4040P
REC/2ABC057044 TC4511BP TC74RC373P TC74RC373P TC74RC373P TC74RC4P	A8	KEC/2ABD018078	TC74HC139P
A11 KEC/2ABD018102 A12 KEC/2ABD018169 A13 KEC/2AAG021014 A14 KEC/2ABD018169 A16 KEC/2AAG049161 A17 TOT4HC04P A18 KEC/2AAG049161 A19 KEC/2AAG049179 A19 KEC/2AAG049179 A20 KEC/2AAG037012 A21 KEC/2AAG037012 BA718 BA22 KEC/2AAG039015 A22 KEC/2AAG039015 A23 KEC/2AG03391 C3 KEC/2CED001512 C4 thru C6 KEC/2CCF001512 C6 KEC/2CAK005391 C7 KEC/2CAG05391 C8 KEC/2CAG05391 C9 KEC/2CAG05391 C1 KEC/2CAG05391 C6 KEC/2CAG05391 C7 KEC/2CAG05391 C8 KEC/2CAG05391 C9 KEC/2CAG05391 C9 KEC/2CAG05391 C10 KEC/2CAG05391	A 9	KEC/2ABD018052	TC74HC74P
REC/2ABD018169 TC74HC04P TD62004P TD62004P TC74HC04P TD62004P TC74HC04P TT74HC04P TC74HC04P TC	A10	KEC/2ABC057044	TC4511BP
### MEC/2AAG021014 ### KEC/2AAG049161 ### KEC/2AAG049161 ### KEC/2AAG049179 ### KEC/2CAAG049171 ### KEC/2CAAG05391 ### KEC/2CAAG05235 ### KEC/2CAAG05235 ### KEC/2CAAG05235 ### KEC/2CAAG05235 ### KEC/2CAAG05231 ### KEC/2CAGG05231 ### KEC/2CAAG05231 ### KEC/2CAAG05231 ### KEC/2CAGG05231 ### KEC/2CAGG05232 ### KEC/2CAGG05232 ### KEC/2CAGG05232 #### KEC/2CAGG05232	A11	KBC/2ABD018102	TC74HC373P
NEC/2ABD018169 NEC/2ABD018169 NEC/2ABD018169 NEC/2ABD018169 NEC/2ABD049161 NEC/2ABD037012 NEC/2ABD037012 NEC/2ABD037012 NEC/2ABD037012 NEC/2ABD037012 NEC/2ABD037012 NEC/2ABD037012 NEC/2ABD037012 NEC/2CBJ001270 NEC/2CBJ001270 NEC/2CBJ001270 NEC/2CBJ001270 NEC/2CCF001512 NEC/2CCF001512 NEC/2CCD025012 NEC/2CD025012 NEC/2CD03525 NEC/2CD03525 NEC/2CD03525 NEC/2CBJ001270 NEC/2CCF001520 NEC/2CCF001520 NEC/2CCF001520 NEC/2CCF001520 NEC/2CD0391 NEC/2CCF001520 NEC/2CD0391 NEC/2CCD0391 NEC/2CCCD0391 NEC/2CCCCD0391 NEC/2CCCCD0391 NEC/2CCCCD0391 NEC/2CCCCD0391 NEC/2CCCCD0391 NEC/2CCCCD0391 NEC/2CCCCD0391 NEC/2CCCCD0391 NEC/2CCCCD0391 NEC/2CCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCC	A12	KEC/2ABD018169	TC74HC04P
NEC/2AAB049161 NEC/2AAB049161 NEC/2AAB049179 NEC/2AB037012 TC4053BP SEC/2AAB020011 SAT18 SEC/2AAB039015 SA222 SEC/2ABC037012 SAT18 SEC/2ABC037012 SAT18 SEC/2ABC037012 SEC/2ABC037012 SEC/2CECO01512 SEC/2CECO01512 SEC/2CECO01512 SEC/2CECO01512 SEC/2CECO01512 SEC/2CECO01520 SEC/2CECO01012 SEC/2CECO0101	A13	KEC/2AAG021014	TD62004P
### ### ##############################	A14	KEC/2ABD018169	TC74HC04P
REC/2ABC037012 REC/2ABC037012 REC/2ABC037012 REC/2ABC037012 REC/2ABC037012 REC/2ABC037012 REC/2ABC037012 REC/2CBC001270 REC/2CBC001270 REC/2CBC001512 Fixed, tantalum 204M3502-105MB ±20%. REC/2CCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCCC	and	KEC/2AAE049161	VTG-REG AN78L05
A19 KEC/2ABC037012 TC4053BP A20 KEC/2AAB020011 BA718 A21 KEC/2AAB039015 BA222 KEC/2ABC037012 BA718 C1 KEC/2CBJ001270 Fixed, elect A1 KMA10VB100M. C2 KEC/2CK005391 Ceramic chip, 0.01 uF. Fixed, tantalum 204M3502-105MB ±20%. C6 KEC/2CCD025012 Fixed, tantalum 204M3502-106M ±20%. C7 KEC/2CAK005235 Ceramic chip RH 47P ±0.5 pF, 50V. C8 KEC/2CAK005110 Ceramic chip CH 10P ±0.5 pF, 50V. C9 and C10 KEC/2CCF001520 Fixed, tantalum 204M3502-106M ±20%. C11 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C12 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C22 KEC/2CDC001012 Fixed, film, ECQ-VIH104JZ9 0.1 uF ±5%, 50V. C23 KEC/2CDC001087 Fixed, film, ECQ-BHH102JZ9 1000 pF ±5%, 50V. C26 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C27 KEC/2CCF003041 Fixed, film, ECQ-BHH02JZ9 1000 pF ±5%, 50V. C28 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005510 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK00520 Ceramic chip, 100 pF RH ±5%, 50V. C30 KEC/2CAK005292 Ceramic chip, 22 pF CH ±5%, 50V. C31 KEC/2CAK005290 Ceramic chip, 470 pF RH ±5%, 50V. C32 KEC/2CAK005290 Ceramic chip, 470 pF RH ±5%, 50V. C23 KEC/2CAK005290 Ceramic chip, 47 pF RH ±5%, 50V.	A18	KEC/2AAE049179	VTG-REG AN79L05
A20 KEC/2AAB020011 A21 KEC/2AAB020015 BA222 KEC/2ABC037012 BA718			
A22		1 1	
REC/2ABC037012 BA718	A21		
C1 KEC/2CBJ001270 Fixed, elect A1 KMA10VB100M. C2 KEC/2CAK005391 Ceramic chip, 0.01 uF. KEC/2CCP001512 Fixed, tantalum 204M3502-105MB ±20%. KEC/2CCD025012 Fixed, tantalum 204M3502-106M ±20%. C3 KEC/2CAK005235 Ceramic chip RH 47P ±0.5 pF, 50V. C4 KEC/2CAK005110 Ceramic chip CH 10P ±0.5 pF, 50V. C5 KEC/2CAK005110 Ceramic chip CH 10P ±0.5 pF, 50V. C6 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C11 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C22 KEC/2CDC001012 Fixed, film, ECQ-V1H104JZ9 0.1 uF ±5%, 50V. C23 KEC/2CDC001087 Fixed, film, ECQ-B1H102JZ9 1000 pF ±5%, 50V. C26 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C27 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C28 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005250 Ceramic chip, 0.01 uF ±5%, 50V. C30 KEC/2CAK005292 Ceramic chip, 22 pF CH ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C32 KEC/2CAK005290 Ceramic chip, 470 pF RH ±5%, 50V. C4 Ceramic chip, 470 pF RH ±5%, 50V.	A22	1	
C1 KEC/2CBJ001270 Fixed, elect A1 KMA10VB100M. C2 KEC/2CAK005391 Ceramic chip, 0.01 uF. KEC/2CCP001512 Fixed, tantalum 204M3502-105MB ±20%. KEC/2CCD025012 Fixed, tantalum 204M3502-106M ±20%. C3 KEC/2CAK005235 Ceramic chip RH 47P ±0.5 pF, 50V. C4 KEC/2CAK005110 Ceramic chip CH 10P ±0.5 pF, 50V. C5 KEC/2CAK005110 Ceramic chip CH 10P ±0.5 pF, 50V. C6 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C11 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C22 KEC/2CDC001012 Fixed, film, ECQ-V1H104JZ9 0.1 uF ±5%, 50V. C23 KEC/2CDC001087 Fixed, film, ECQ-B1H102JZ9 1000 pF ±5%, 50V. C26 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C27 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C28 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005250 Ceramic chip, 0.01 uF ±5%, 50V. C30 KEC/2CAK005292 Ceramic chip, 22 pF CH ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C32 KEC/2CAK005290 Ceramic chip, 470 pF RH ±5%, 50V. C4 Ceramic chip, 470 pF RH ±5%, 50V.			
C2 KEC/2CAK005391 Ceramic chip, 0.01 uF. C3 KEC/2CCF001512 Pixed, tantalum 204M3502-105MB ±20%. C4 thru C6 KEC/2CAK005235 Ceramic chip RH 47P ±0.5 pF, 50V. C8 KEC/2CAK005110 Ceramic chip CH 10P ±0.5 pF, 50V. C9 and C10 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C11 thru C22 KEC/2CAK005391 Fixed, film, ECQ-V1H104JZ9 0.1 uF ±5%, 50V. C23 and C24 KEC/2CAK005391 Fixed, film, ECQ-B1H102JZ9 1000 pF ±5%, 50V. C26 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C27 KEC/2CAK005391 Fixed, film, ECQ-B1H102JZ9 1000 pF ±5%, 50V. C28 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C30 KEC/2CAK005250 Ceramic chip, 0.01 uF ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 22 pF CH ±5%, 50V. C32 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C63 KEC/2CAK005230 Ceramic chip, 470 pF RH ±5%, 50V. C64 Ceramic chip, 470 pF RH ±5%, 50V. C65 Ceramic chip, 470 pF RH ±5%, 50V. C66 Ceramic chip, 470 pF RH ±5%, 50V. C67 Ceramic chip, 470 pF RH ±5%, 50V.	01	WBC /000 1001 000	
REC/2CCF001512 Fixed, tantalum 204M3502-105MB ±20%.			,
REC/2CCD025012 Fixed, tantalum 204M3502-106M ±20%.			
thru C6 C7			=
C8 KEC/2CAK005110 Ceramic chip CH 10P ±0.5 pF, 50V. Fixed, tantalum 204M3502-106M ±20%. C11 KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. C22 KEC/2CDC001012 Fixed, film, ECQ-V1H104JZ9 0.1 uF ±5%, 50V. C23 KEC/2CDC001087 Fixed, film, ECQ-BH102JZ9 1000 pF ±5%, 50V. C26 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C27 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C28 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C30 KEC/2CAK005250 Ceramic chip, 100 pF RH ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 22 pF CH ±5%, 50V. C32 KEC/2CAK005293 Ceramic chip, 470 pF RH ±5%, 50V. C33 KEC/2CAK005230 Ceramic chip, 47 pF RH ±5%, 50V.	thru	ABC/ 2000/20012	riacu, tantarum 204233022-1002 ±20%.
ESC/2CCF001520 Fixed, tantalum 204M3502-106M ±20%. KEC/2CAK005391 Ceramic chip, 0.01 uF 10%, 50V. Fixed, film, ECQ-V1H104JZ9 0.1 uF ±5%, 50V. KEC/2CDC001087 Fixed, film, ECQ-BH102JZ9 1000 pF ±5%, 50V. Ceramic chip, 0.01 uF ±10%, 50V. Fixed, tantalum 204M3502-106M ±20%. Ceramic chip, 0.01 uF ±10%, 50V. Ceramic chip, 0.01 uF ±10%, 50V. Ceramic chip, 0.01 uF ±10%, 50V. Ceramic chip, 0.01 uF ±5%, 50V. Ceramic chip, 0.01 uF ±5%, 50V. Ceramic chip, 0.01 uF ±5%, 50V. Ceramic chip, 100 pF RH ±5%, 50V. Ceramic chip, 22 pF CH ±5%, 50V. Ceramic chip, 470 pF RH ±5%, 50V. Ceramic chip, 2200 pF ±10%, 50V. Ceramic chip, 47 pF RH ±5%, 50V.	C 7	KEC/2CAK005235	Ceramic chip RH 47P ±0.5 pF, 50V.
And C10 C11 C11 C11 C11 C12 C12 C13 KEC/2CAK005391 C14 C15 C15 C16 C17 C18 C18 C19	28	KEC/2CAK005110	Ceramic chip CH 10P ±0.5 pF, 50V.
thru C22 C23 KEC/2CDC001012 Fixed, film, ECQ-V1H104JZ9 0.1 uF ±5%, 50V. C25 KEC/2CDC001087 Fixed, film, ECQ-B1H102JZ9 1000 pF ±5%, 50V. C26 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C27 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005250 Ceramic chip, 100 pF RH ±5%, 50V. C30 KEC/2CAK005292 Ceramic chip, 22 pF CH ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C33 KEC/2CAK005293 Ceramic chip, 2200 pF ±10%, 50V. Ceramic chip, 47 pF RH ±5%, 50V.	and	KEC/2CCF001520	Fixed, tantalum 204M3502-106M ±20%.
### Acceptable of the control of the	thru	KEC/2CAK005391	Ceramic chip, 0.01 uF 10%, 50V.
C26 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C27 KEC/2CCF003041 Fixed, tantalum 204M3502-106M ±20%. C28 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005250 Ceramic chip, 100 pF RH ±5%, 50V. C30 KEC/2CAK005151 Ceramic chip, 22 pF CH ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C32 KEC/2CAK005529 Ceramic chip, 2200 pF ±10%, 50V. C33 KEC/2CAK005230 Ceramic chip, 47 pF RH ±5%, 50V.	and	KEC/2CDC001012	Fixed, film, ECQ-V1H104JZ9 0.1 uF ±5%, 50V.
C26 KEC/2CAK005391 C27 KEC/2CCF003041 KEC/2CAK005391 C28 KEC/2CAK005391 C29 KEC/2CAK005250 C30 KEC/2CAK005151 C31 KEC/2CAK005292 C32 KEC/2CAK005529 C33 KEC/2CAK005529 C4 Fixed, tantalum 204M3502-106M ±20%. C4 Ceramic chip, 0.01 uF ±10%, 50v. C5 Ceramic chip, 100 pF RH ±5%, 50v. C6 Ceramic chip, 22 pF CH ±5%, 50v. C6 Ceramic chip, 470 pF RH ±5%, 50v. C6 Ceramic chip, 2200 pF ±10%, 50v. C6 Ceramic chip, 47 pF RH ±5%, 50v.	25	KEC/2CDC001087	Fixed, film, ECQ-B1H102JZ9 1000 pF +5%, 50v.
C27 KEC/2CF003041 Fixed, tantalum 204M3502-106M ±20%. C28 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005250 Ceramic chip, 100 pF RH ±5%, 50V. C30 KEC/2CAK005151 Ceramic chip, 22 pF CH ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C32 KEC/2CAK005292 Ceramic chip, 2200 pF ±10%, 50V. C33 KEC/2CAK005230 Ceramic chip, 47 pF RH ±5%, 50V.	26	KEC/2CAK005391	_
C28 KEC/2CAK005391 Ceramic chip, 0.01 uF ±10%, 50V. C29 KEC/2CAK005250 Ceramic chip, 100 pF RH ±5%, 50V. C30 KEC/2CAK005151 Ceramic chip, 22 pF CH ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C32 KEC/2CAK005529 Ceramic chip, 2200 pF ±10%, 50V. C33 KEC/2CAK005230 Ceramic chip, 47 pF RH ±5%, 50V.	27	KEC/2CCF003041	-
C29 KEC/2CAK005250 Ceramic chip, 100 pF RH ±5%, 50V. C30 KEC/2CAK005151 Ceramic chip, 22 pF CH ±5%, 50V. C31 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C33 KEC/2CAK005230 Ceramic chip, 2200 pF ±10%, 50V. C33 KEC/2CAK005230 Ceramic chip, 47 pF RH ±5%, 50V.	28	KEC/2CAK005391	-
C31 KEC/2CAK005292 Ceramic chip, 470 pF RH ±5%, 50V. C32 KEC/2CAK005529 Ceramic chip, 2200 pF ±10%, 50V. C33 KEC/2CAK005230 Ceramic chip, 47 pF RH ±5%, 50V.	29	KEC/2CAK005250	
Ceramic chip, 2200 pF ±10%, 50V. KEC/2CAK005230 Ceramic chip, 47 pF RH ±5%, 50V.	30	KEC/2CAK005151	- ·
33 KEC/2CAK005230 Ceramic chip, 47 pF RH ±5%, 50v.	31	KEC/2CAK005292	· · · · · · · · · · · · · · · · · · ·
	32	KEC/2CAK005529	Ceramic chip, 2200 pF ±10%, 50V.
35 KEC/CCF001470 Fixed, tantalum, 204M1602-475M.	33	KEC/2CAK005230	-
	35	KEC/CCF001470	Fixed, tantalum, 204M1602-475M.

SYMBOL	PART NO.	DESCRIPTION
CR1	KEC/2QBE005011	Silicon DAN202K.
CR2	KEC/2QBB001737	Zener HZ-7B1.
CR3 thru CR8	KEC/2QBE005037	Silicon DA204k.
CR9	KEC/2QBA006161	Silicon 182075K.
CR10	KEC/2QBE005037	Silicon DA204K.
J1	KEC /2004012024	TI-B-10D-8000
J2	KEC/2PDA012026 KEC/2PDA012018	IL-8-10P-83TA-EF IL-8-8P-83TA-EF
J3	KEC/2PDA012034	IL-8-13P-93T3-EP
and J4	,	
J5	KEC/2PDA012281	IL-8-6P-8273-8F
JP1	KEC/2PDD003774	P8-3PF-8471-4KL1
P1	KEC/2PDE002056	P8-25H4-1
Q1	KEC/2QAD001039	Silicon 28C2 52LC.
and Q2		
Q3	KEC/2QAA011390	Silicon 25AliplSC.
Q7 thru	KEC/2QAD001039	Silicon 28C2 2LC.
Q11		
R1 thru	KEC/2RGC001275	Square chip, /8W, 47K ohm ±5%.
R5		
R6	KEC/2RGC001242	Square chip, 3/8W, 22K ohm ±5%.
R7	KEC/2RGC001218	Square chip, 8/8W, 100K ohm ±5%.
R8	KEC/2RGC001275	Square chip, 4/8W, 47K ohm ±5%.
R10	KEC/2RGC001275	Square chip. /8W, 47K ohm ±5%.
R11 thru R15	KEC/2RGC001119	Square chip, 1/8W, 220 ohm ±5%.
R16	KEC/2RGC001218	Square chip, 48W, 10K ohm ±5%.
thru R19	,	
R20	KEC/2RGC001119	Square chip, 3/8W, 220 ohm <u>+</u> 5%.
R21 thru	KEC/2RGC001093	Square chip, 2/8w, 100 ohm ±5%.
R27	FBC/0DCC001057	
R28 R29	KEC/2RGC001275 KEC/2RGC001176	Square chip, 1/8W, 47K ohm ±5%.
130	KEC/2RGC001176	Square chip, 1/8w, 2.2K ohm +5%. Square chip, 1/8w, 470K ohm +5%.
131	KEC/2RGC001341	Square chip, 1/8W, 470K ohm +5%.
132	KEC/2RGC001028	Square chip, 1/8w, 10 chm ±5%.
133	KEC/2RGC001218	Square chip, 1/8W, 10K ohm +5%.
thru 136		•
137	KEC/2RGC001275	Square chip, 1/8W, 47K ohm ±5%.
138	KEC/2RGC001242	Square chip, 1/8W, 22K ohm ±5%.
139	KEC/2RGC001275	Square chip, 1/8w, 47K ohm ±5%.
40	KEC/2RGC001242	Square chip, 1/8w, 22K ohm ±5%.
41 hru 43	KEC/2RGC001275	Square chip, 1/8W, 47K ohm ±5%.
44	KEC/2RGC001176	Square chip, 1/8W, 2.2K ohm +5%.
45	KEC/2RGC001218	Square chip, 1/8W, 10K ohm ±5%.
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	SYMBOL	PART NO.	DESCRIPTION
7	R47	KEC/2RGC001309	Square chip, 1/8W, 100K ohm ±5%.
	R48	KEC/2RGC001127	Square chip, 1/8W, 330 ohm ±5%.
	R49 and R50	KBC/2RGC001218	Square chip, 1/8W, 10K ohm ±5%.
ı	R51	KEC/2RGC001242	Square chip, 1/8W, 22K ohm ±5%.
1	R52	KEC/2RFB017068	Variable, 10K ohm ±30%, Mod Adjust.
١	R53	KEC/2RGC001010	Square chip, 1/8W, 0 ohm ±5%.
١	R54	KEC/2RGC001275	Square chip, 1/8W, 47K ohm ±5%.
-	R55	KEC/2RGC001010	Square chip, 1/87, 0 ohm ±5%.
	R56 and R57	KEC/2RGC001189	Square chip, 1/8W, 3.3K ohm ±5%.
1	R58	KEC/2RGC001010	Square chip, 1/8W, 0 ohm ±5%.
	R59	KEC/2RGC001275	Square chip, 1/87, 47% ohm ±5%.
	R60	KEC/2RGC001036	Square chip, 1/87, 10 ohm ±5%.
	R61 and R62	KEC/2RGC001242	Square chip, 1/8W, 22K ohm ±5%.
ı	R63	KEC/2RGC001275	Square chip, 1/8W, 47K ohm +5%.
-	R64	KEC/2RGC001218	Square chip, 1/8W, 100K ohm ±5%.
	R65 thru R67	KEC/2RGC001317	Square chip, 1/8W, 150K ohm ±5%.
	R68	KEC/2RGC001010	Square chip, C ohm.
1	R69	KEC/2RGC001036	Square chip, 1/8W, 10 ohm ±5%.
1	R70	KEC/2RGC001309	Square chip, 1/8W, 100K ohm ±5%.
-	RA1 and RA2	KEC/2REA020116	EXB-P88-473K
- 1			
ı	XA3	KEC/2PDH001241	IC03T-280684
1	XA4	KEC/2PDH001282	ICO3T-240684
1			10001 #10001
ı			QUARTZ CRYSTAL
1	¥1	KEC/2YAA181632	HC-43/U-4, 8.192 MHz.
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